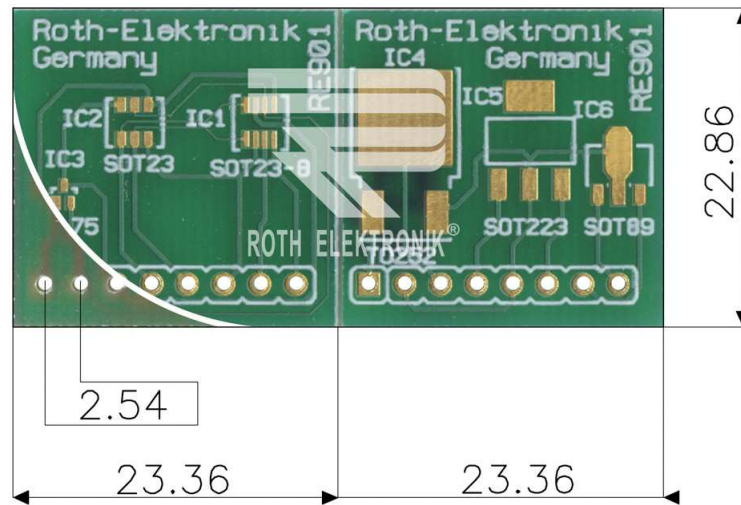


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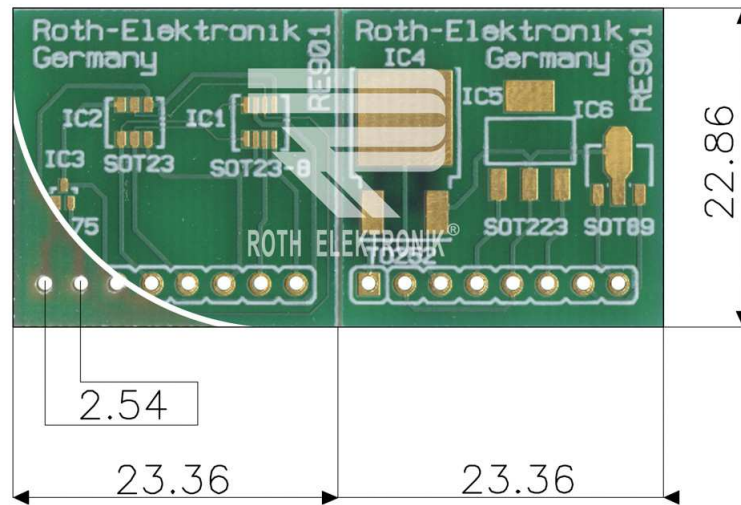
#### RE901

- Multiadapter circuit board with six micro-miniature semiconductor circuits
- Epoxy fibre-glass FR4 1.50 mm
- Single-sided 35 µm Cu
- Surface chem. Ni/Au with solder stop mask
- Component print
- The PCB can be equipped with twenty different types of semiconductors listed in the table
- 8-pole pin terminal connection spacing 2.54 mm
- Hole diameter 1.00 mm
- Prescratched rated break point for the separation of individual moduls from the board
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- Size 22.86 mm x 46.72 mm

Layout Pad (mm) Pitch Size Configuration Occupation

TO252 \* \* \* \* TO252SOT223 \* \* \* \* SOT223SOT89 \* \* \* \* SOT89ASOT23 0.710 x 1.000 0.950 mm 2.400 mm 2 Reihen x 3 SC59, SC74, SC74A, SMT3, SMT5, SMT6, SOT23, SOT23-5, SOT23-6SOT23-8 0.460 x 1.100 0.650 mm 2.400 mm 2 Reihen x 4 SC70, SC88A, SOT23-8, UMT3, UMT5, UMT6SC75 \* \* \* \* EMT3, SC75

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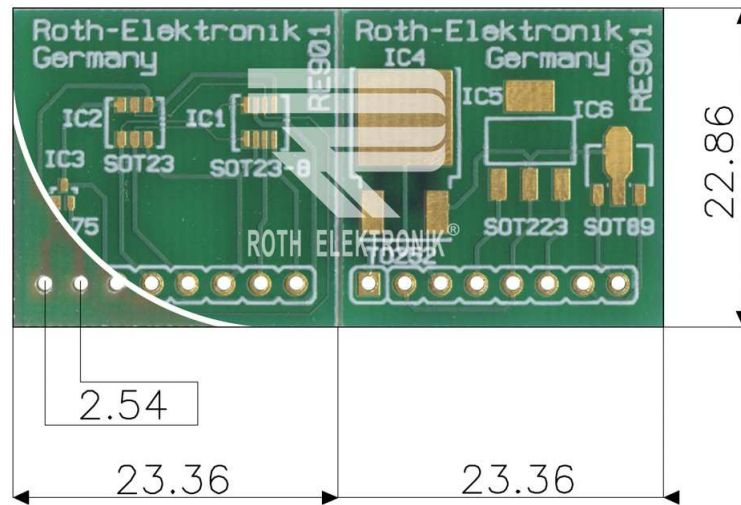
#### RE901

- Multiadapterplatine mit sechs Micro-Miniatur-Halbleiterschaltungen
- Epoxydglashartgewebe FR4 1,50 mm
- Einseitig 35 µm Cu
- Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
- Bestückungsdruck
- Es können 20 verschiedene Halbleitertypen auf der Platine plaziert werden
- 8-poliger Stiftleistenanschluß Raster 2,54 mm
- Lochdurchmesser 1,00 mm
- Vorgeritzte Sollbruchstelle zum Trennen der Module
- Gerberdaten zur Herstellung des Lötpastenaufdrucks werden auf Anfrage zur Verfügung gestellt
- Größe 22,86 x 46,72 mm

Layout Pad (mm) Pitch Größe Konfiguration Belegung

TO252 \* \* \* \* TO252SOT223 \* \* \* \* SOT223SOT89 \* \* \* \* SOT89ASOT23 0,710 x 1,000 0,950 mm 2,400 mm 2 Reihen x 3 SC59, SC74, SC74A, SMT3, SMT5, SMT6, SOT23, SOT23-5, SOT23-6SOT23-8 0,460 x 1,100 0,650 mm 2,400 mm 2 Reihen x 4 SC70, SC88A, SOT23-8, UMT3, UMT5, UMT6SC75 \* \* \* \* EMT3, SC75

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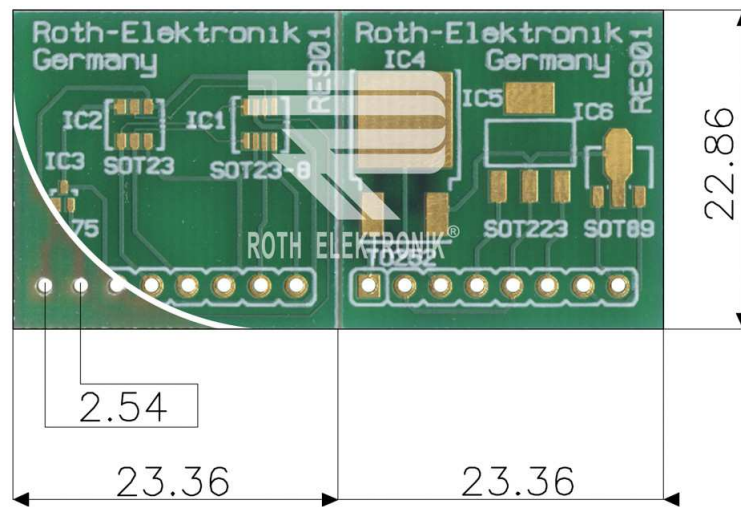
#### RE901

- Platine à adaptateur multiple doté de six éléments semi-conducteurs micro-miniature
- Fibre de verre époxyde FR4 1,50 mm
- Simple face 35 µm Cu
- Surface avec Ni/Au chimique et un laque d'arrêt de soudure
- Impression d'insertion
- Le placement de 20 différents types de semi-conducteurs énoncés dans le tableau est possible sur la platine
- Baguette à 8 broches pas 2,54 mm
- Perforation 1,00 mm Ø
- Point destiné à la rupture de séparation des modules
- Les données Data Gerber d'apprêt pour l'établissement de l'application de pâte à braser seront mis à la disposition gratuitement
- Dimensions 22,86 mm x 46,72 mm

Layout Pad (mm) Pitch Taille Configuration Occupation

TO252 \*\*\*\* TO252SOT223 \*\*\*\* SOT223SOT89 \*\*\*\* SOT89ASOT23 0,710 x 1,000 0,950 mm 2,400 mm 2 Reihen x 3 SC59, SC74, SC74A, SMT3, SMT5, SMT6, SOT23, SOT23-5, SOT23-6SOT23-8 0,460 x 1,100 0,650 mm 2,400 mm 2 Reihen x 4 SC70, SC88A, SOT23-8, UMT3, UMT5, UMT6SC75 \*\*\*\* EMT3, SC75

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#### RE901

- Placa de circuito impreso de multiadaptador con seis circuitos de semiconductor en microminiatura
- Fibra de vidrio epoxídica FR4 1,50 mm
- Por un lado 35 µm de Cu
- Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
- Impresión de posición por el lado de los componentes
- En la placa de circuito impreso se pueden incorporar veinte tipos distintos de semiconductores indicados en la tabla
- Conexión de regleta de clavijas de 8 polos trama de agujeros 2,54 mm
- Diámetro de agujeros 1,00 mm
- Punto de ruptura controlada premarcado para separar los módulos
- Datos (Gerber) de curtición para la abricación de la máscara de soldadura y de la impresión de la pasta de soldadura se pondrán a disposición gratuitamente bajo demanda
- Tamaño 22,86 mm x 46,72 mm

Layout Pad (mm) Pitch Tamaño Configuración Ocupación

TO252 \*\*\*\* TO252SOT223 \*\*\*\* SOT223SOT89 \*\*\*\* SOT89ASOT23 0,710 x 1,000 0,950 mm 2,400 mm 2 Reihen x 3 SC59, SC74, SC74A, SMT3, SMT5, SMT6, SOT23, SOT23-5, SOT23-6SOT23-8 0,460 x 1,100 0,650 mm 2,400 mm 2 Reihen x 4 SC70, SC88A, SOT23-8, UMT3, UMT5, UMT6SC75 \*\*\*\* EMT3, SC75